

# **Product Change Notification - LIAL-08TVGL467**

#### Date:

02 Apr 2018

# **Product Category:**

8-bit PIC Microcontrollers; 16-Bit - Microcontrollers and Digital Signal Controllers; USB Bridge; USB Power Delivery

### **Affected CPNs:**

# **Notification subject:**

CCB 3262, 3262.001-3262.003 Initial Notice: Qualification of CuPdAu wire in selected products of the 200K wafer technology available in different QFN packages at MTAI assembly site.

#### **Notification text:**

**PCN Status:** 

Initial notification. **PCN Type:** Manufacturing

Change

# **Microchip Parts Affected:**

Please open one of the icons found in the Affected CPNs section above.

**NOTE:** For your convenience Microchip includes identical files in two formats (.pdf and .xls)

# **Description of Change:**

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 200K wafer technology available in 28L QFN-S (6x6mm), 28L QFN (6x6mm), 20L QFN (5x5mm), 16L QFN (4x4mm), 20L QFN (4x4mm) and 16L QFN (3x3mm) packages at MTAI assembly site.

### Pre Change:

Using gold (Au) bond wire

# **Post Change:**

Using palladium coated copper with gold flash(CuPdAu) bond wire.

## **Pre and Post Change Summary:**

	Pre Change Post Change								
Assembly Site	Microchip Technology Thailand HQ (MTAI)	Microchip Technology Thailand HQ (MTAI)							
Wire material	Au	CuPdAu							
Die attach material	3280	3280							
Molding compound material	G700LTD	G700LTD							
Lead frame material	A194	A194							

#### **Impacts to Data Sheet:**

None

#### **Change Impact:**

None

#### **Reason for Change:**

To improve on-time delivery performance by qualifying palladium coated copper with gold flash (CuPdAu) bond wire.

# **Change Implementation Status:**



In Progress

## **Reason for Change:**

To improve on-time delivery performance by qualifying palladium coated copper with gold flash (CuPdAu) bond wire

## **Change Implementation Status:**

In Progress

# **Estimated Qualification Completion Date:**

April 2018

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

# **Time Table Summary:**

		March 2018				April 2018				
Workweek	09	10	11	12	13	14	15	16	17	18
Initial PCN Issue Date					Х					
Qual Report Availability								Χ		
Final PCN Issue Date								Х		

# **Method to Identify Change:**

Traceability code

#### **Qualification Plan:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual Plan.

#### **Revision History:**

March 27, 2018: Issued initial notification.

April 02, 2018: Re-issued initial notification to correct the time table summary.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

# Attachment(s):

PCN\_LIAL-08TVGL467\_QUAL PLAN.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

#### **Terms and Conditions:**

If you wish to change your product/process change notification (PCN) profile please log on to our website at microchip.com/PCN sign into myMICROCHIP to open the myMICROCHIP home page, then select a profile option from the left navigation bar.

To opt out of future offer or information emails (other than product change notification emails), click here to go to microchip DIRECT and login, then click on the "My account" link, click on "Update profile" and un-check the box that states "Future offers or information about Microchip's products or services."

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#### Affected Catalog Part Numbers (CPN)

PIC16F1503-E/MGVAO

PIC16F1503-H/MGVAO

PIC16F1503-I/MGVAO

PIC16F1503T-E/MGVAO

PIC16F1503T-H/MGVAO

PIC16F1503T-I/MGVAO

PIC16F1507-H/MLVAO

PIC16F1507T-H/MLVAO

PIC16F1508-E/MLVAO

PIC16F1508-H/MLVAO

PIC16F1508T-E/MLVAO

PIC16F1508T-H/MLVAO

PIC16F1508T-I/MLVAO

PIC16F1509-E/MLVAO

PIC16F1509T-E/MLVAO

PIC16F1509T-I/MLVAO

PIC16F1704-E/MLVAO

PIC16F1704-I/MLVAO

PIC16F1704T-E/MLVAO

PIC16F1704T-I/MLVAO

PIC16F1705-I/MLVAO

PIC16F1705T-I/MLVAO

PIC16F1718-I/MLVAO

PIC16F1718T-I/MLVAO

PIC16F1764T-E/MLVAO

PIC16F1783T-E/MLVAO

PIC16F1786-E/MLVAO

PIC16F1786-I/MLVAO

PIC16F1786T-E/MLVAO

PIC16F1786T-I/MLVAO

PIC16F1788-E/MLVAO

PIC16F1788-I/MLVAO

PIC16F1788T-E/MLVAO

PIC16F1788T-I/MLVAO

PIC16F1823-E/MLVAO

PIC16F1823-I/MLVAO

PIC16F1823T-E/MLVAO

PIC16F1823T-I/MLVAO

PIC16F1824-E/MLVAO

PIC16F1824-H/MLVAO

PIC16F1824-I/MLVAO

PIC16F1824T-E/MLVAO

PIC16F1824T-H/MLVAO

PIC16F1824T-I/MLVAO

PIC16F1825-E/MLVAO

PIC16F1825-I/MLVAO

PIC16F1825T-E/MLVAO

Date: Sunday, April 01, 2018

LIAL-08TVGL467 - CCB 3262, 3262.001-3262.003 Initial Notice: Qualification of CuPdAu wire in selected products of the 200K wafer technology available in different QFN packages at MTAI assembly site.

PIC16F1827-I/MLVAO
PIC16F1828-E/MLVAO
PIC16F1828-H/MLVAO
PIC16F1828-I/MLVAO
PIC16F1828T-E/MLVAO
PIC16F1828T-E/MLVAO

PIC16F1828T-I/MLVAO PIC16F1829-E/MLVAO PIC16F1829-H/MLVAO PIC16F1829-I/MLVAO PIC16F1829T-E/MLVAO PIC16F1829T-H/MLVAO PIC16F1829T-I/MLVAO

PIC16F1938-E/MLVAO PIC16F1938T-E/MLVAO

PIC16F1938T-I/MLVAO

PIC16LF1454-I/MLVAO PIC16LF1454T-I/MLVAO

PIC16LF1554-E/MLVAO

PIC16LF1554-I/MLVAO

PIC16LF1554T-E/MLVAO

PIC16LF1554T-I/MLVAO

PIC16LF1828-I/MLVAO

PIC16LF1828T-E/MLVAO

PIC16LF1828T-I/MLVAO

PIC16LF1829-E/MLVAO

PIC16LF1829-I/MLVAO

PIC16LF1829T-E/MLVAO

PIC16LF1829T-I/MLVAO

PIC16LF1936-E/MLVAO

PIC16LF1936T-E/MLVAO

PIC16LF1938-I/MLVAO

PIC16LF1938T-I/MLVAO

PIC18F14K22-E/MLVAO

PIC18F14K22T-E/MLVAO

PIC18F24K20T-E/MLVAO

PIC18F24K22T-E/MLVAO

PIC18F25K20-I/MLVAO

PIC18F25K20T-E/MLVAO

PIC18F25K20T-I/MLVAO

PIC18F25K22-E/MLVAO

PIC18F25K22T-E/MLVAO

PIC18F25K80-E/MMVAO

PIC18F25K80-H/MMVAO

PIC18F25K80-I/MMVAO

PIC18F25K80T-E/MMVAO

PIC18F25K80T-H/MMVAO

PIC18F25K80T-I/MMVAO

PIC18F26K20-I/MLVAO

Date: Sunday, April 01, 2018

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PIC18F26K22T-E/MLVAO

PIC18F26K80-E/MMVAO

PIC18F26K80T-E/MMVAO

PIC18F26K80T-I/MMVAO

PIC18LF26K22T-E/MLVAO

PIC24F16KA102-E/MLVAO

PIC24F16KA102T-I/MLVAO

PIC24FV16KA302-I/MLVAO

PIC24FV16KA302T-I/MLVAO

UTC2000-E/MG042

UTC2000T-E/MG042

MCP2200-I/MQVAO

MCP2200T-I/MQVAO

MCP2200T-E/MQVAO

Date: Sunday, April 01, 2018